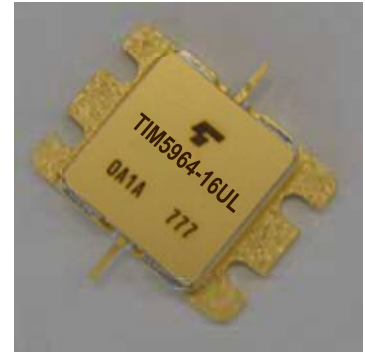


**FEATURES**

- **BROAD BAND INTERNALLY MATCHED FET**
- **HIGH POWER**  
P1dB= 42.5dBm at 5.9GHz to 6.4GHz
- **HIGH GAIN**  
G1dB= 10.0dB at 5.9GHz to 6.4GHz
- **LOW INTERMODULATION DISTORTION**  
IM3= -47dBc at Pout= 31.5dBm (Single Carrier Level)
- **HERMETICALLY SEALED PACKAGE**



**RF PERFORMANCE SPECIFICATIONS ( Ta= 25°C )**

CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Output Power at 1dB Gain Compression Point	P1dB	VDS= 10V IDSset= 3.6A f= 5.9 to 6.4GHz	dBm	41.5	42.5	—
Power Gain at 1dB Gain Compression Point	G1dB		dB	9.0	10.0	—
Drain Current	IDS1		A	—	4.4	5.0
Gain Flatness	ΔG		dB	—	—	±0.6
Power Added Efficiency	ηadd		%	—	36	—
3rd Order Intermodulation Distortion	IM3	Two-Tone Test Po= 31.5dBm, Δf= 5MHz (Single Carrier Level)	dBc	-44	-47	—
Drain Current	IDS2		A	—	4.4	5.0
Channel Temperature Rise	ΔTch	(VDS × IDS + Pin – P1dB) × Rth(c-c)	°C	—	—	80

**Recommended Gate Resistance (Rg): 68 Ω**

**ELECTRICAL CHARACTERISTICS ( Ta= 25°C )**

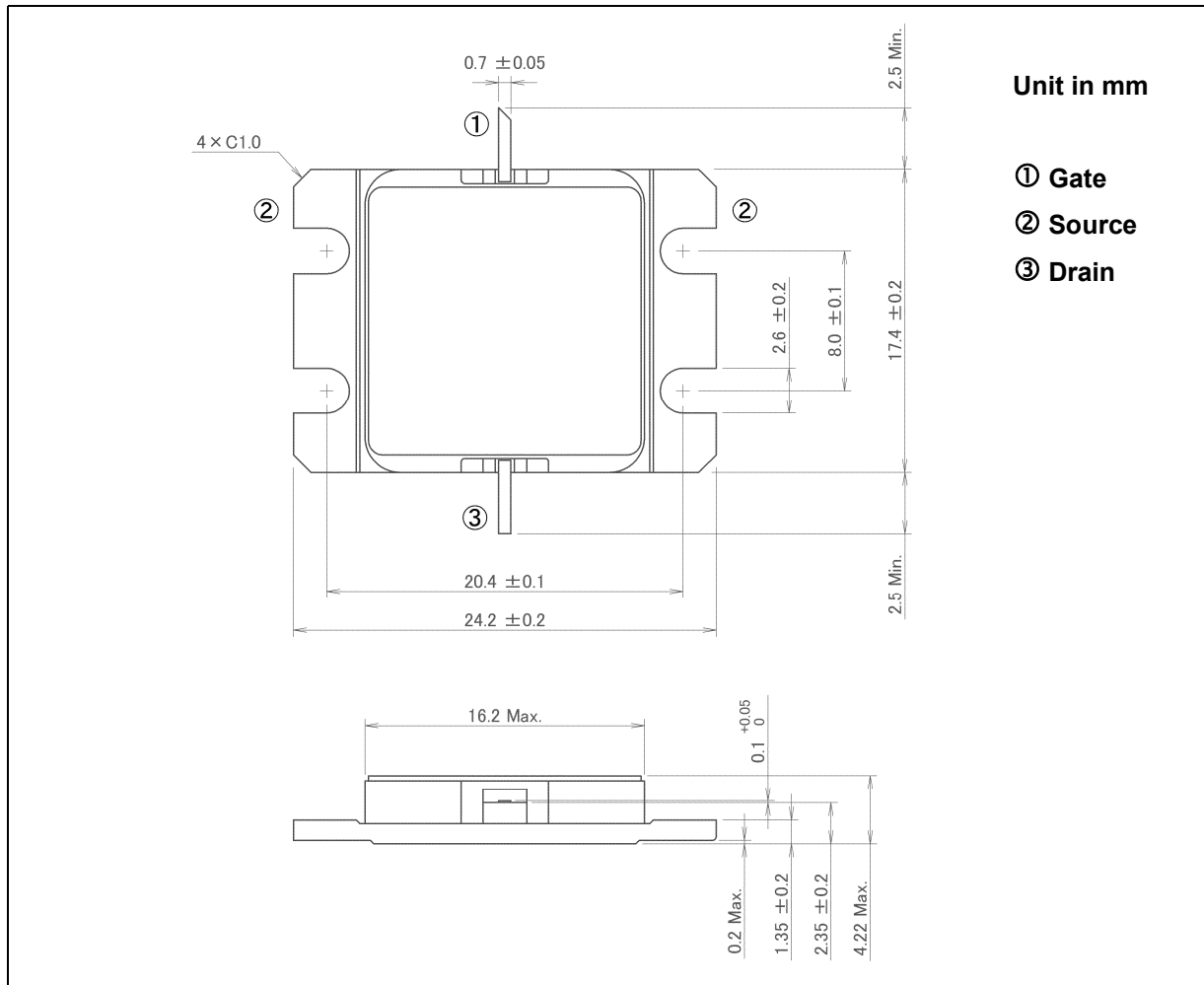
CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Transconductance	gm	VDS= 3V IDS= 6.0A	S	—	3.6	—
Pinch-off Voltage	VGSoff	VDS= 3V IDS= 60mA	V	-1.0	-2.5	-4.0
Saturated Drain Current	IDSS	VDS= 3V VGS= 0V	A	—	10.5	—
Gate-Source Breakdown Voltage	VGSO	IGS= -200μA	V	-5	—	—
Thermal Resistance	Rth(c-c)	Channel to Case	°C/W	—	1.5	1.8

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**ABSOLUTE MAXIMUM RATINGS (Ta= 25°C)**

CHARACTERISTICS	SYMBOL	UNIT	RATING
Drain-Source Voltage	VDS	V	15
Gate-Source Voltage	VGS	V	-5
Drain Current	IDS	A	14.0
Total Power Dissipation (Tc= 25°C)	PT	W	83.3
Channel Temperature	Tch	°C	175
Storage Temperature	Tstg	°C	-65 to +175

**PACKAGE OUTLINE (2-16G1B)**



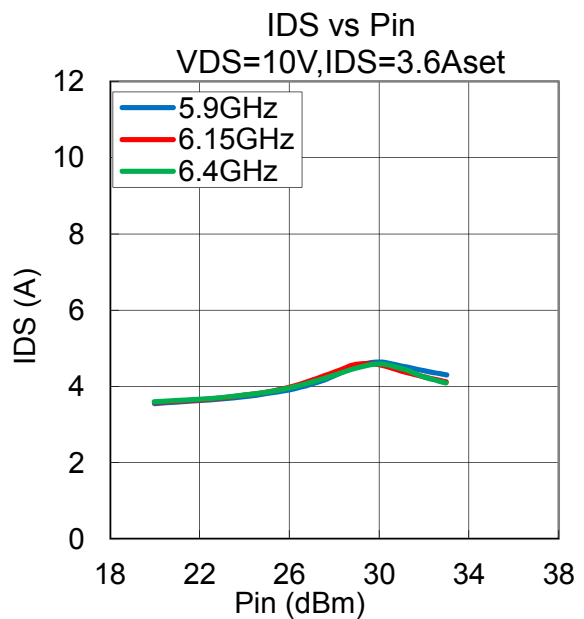
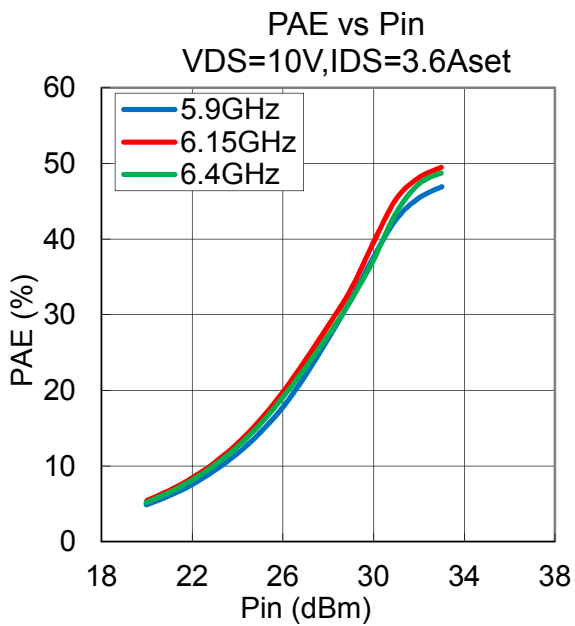
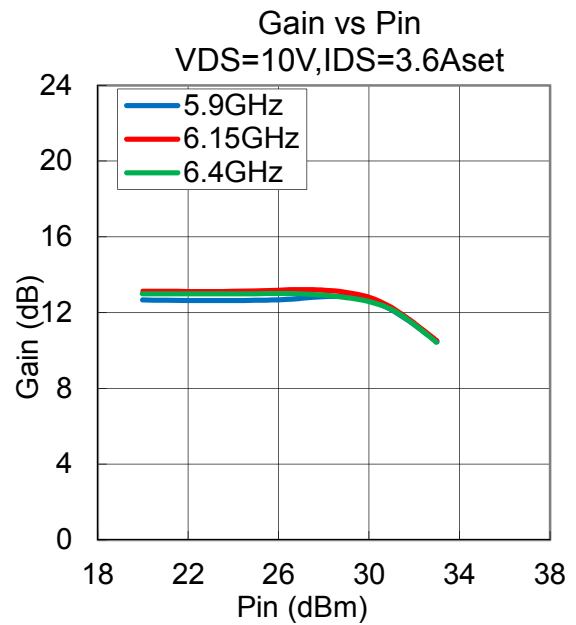
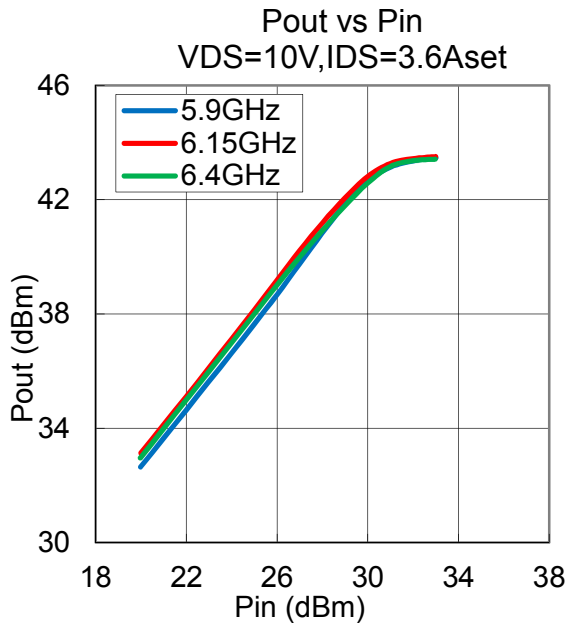
**HANDLING PRECAUTIONS FOR PACKAGE MODEL**

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C or 3 seconds at 350°C.

**TYPICAL RF PERFORMANCE**

·Pout , Gain , PAE , IDS vs. Pin

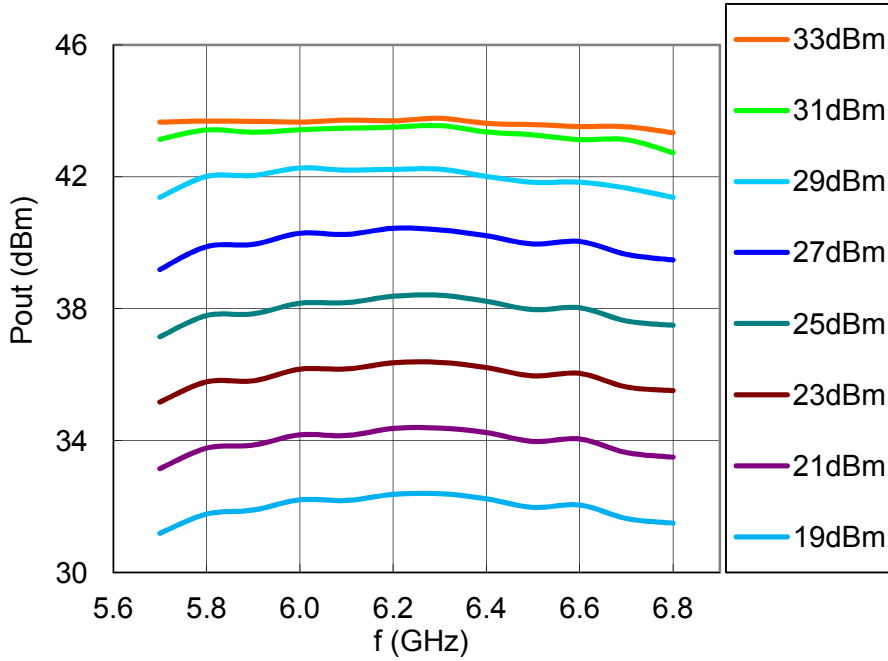
VDS= 10 V, IDSset= 3.6 A, f= 5.9, 6.15, 6.4 GHz, Ta= +25 °C



**-Pout vs. Frequency**

VDS= 10 V, IDSset= 3.6 A, Ta= +25 °C

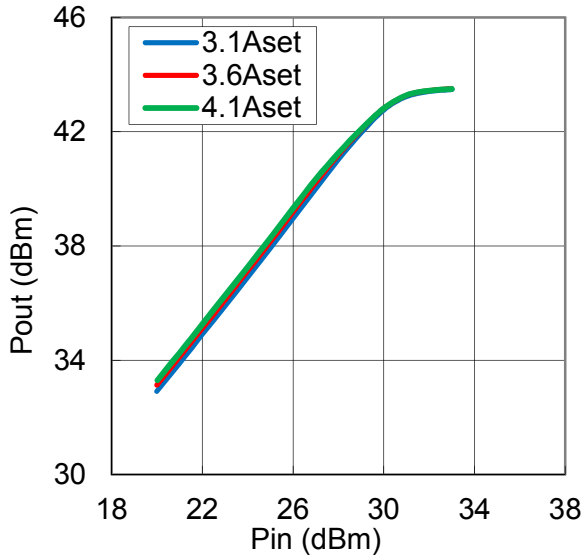
Pout vs Freq  
Vds=10A Ids=3.6Aset



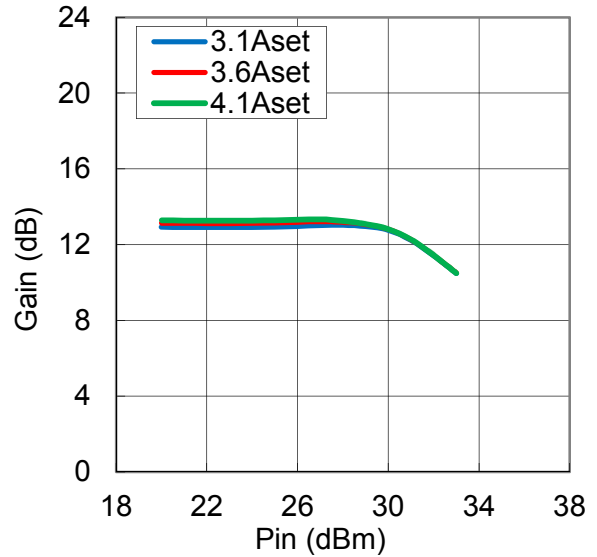
·Pout , Gain , PAE , IDS vs. Pin vs. IDSset

VDS= 10 V, IDSset= 3.1, 3.6, 4.1 A, f= 6.15 GHz, Ta= +25 °C

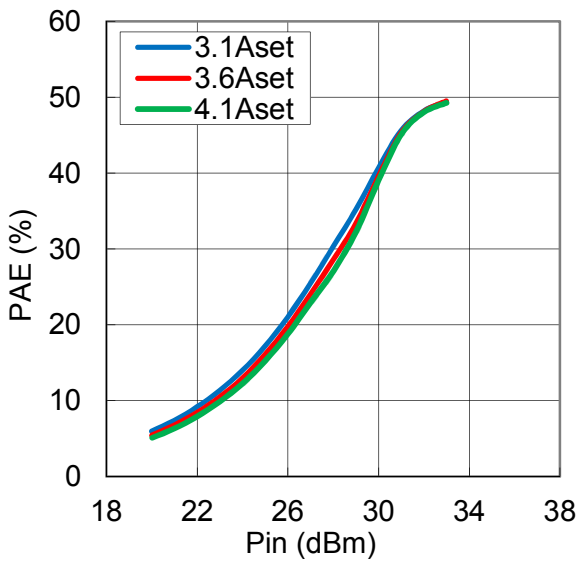
Pout vs Pin  
VDS=10V,f=6.15GHz



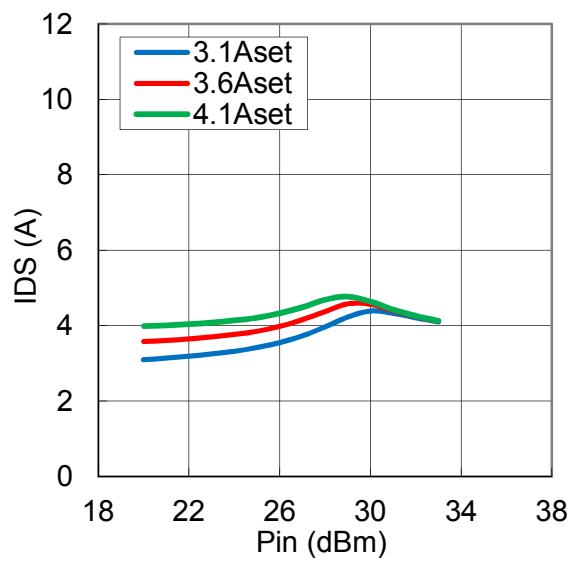
Gain vs Pin  
VDS=10V,f=6.15GHz



PAE vs Pin  
VDS=10V,f=6.15GHz

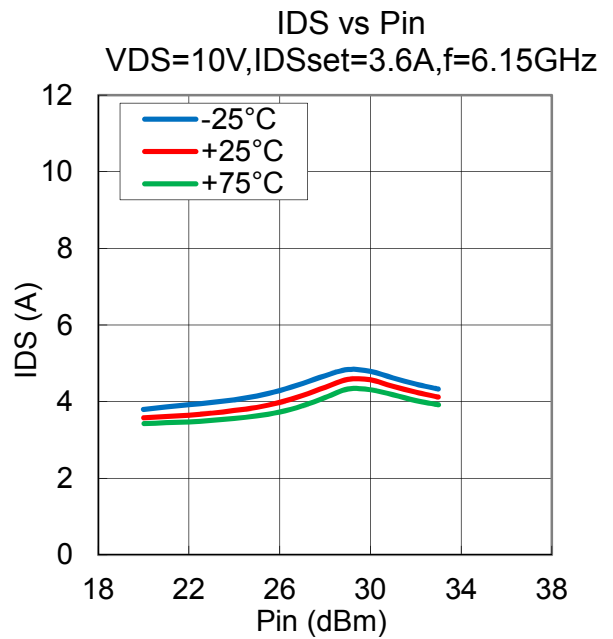
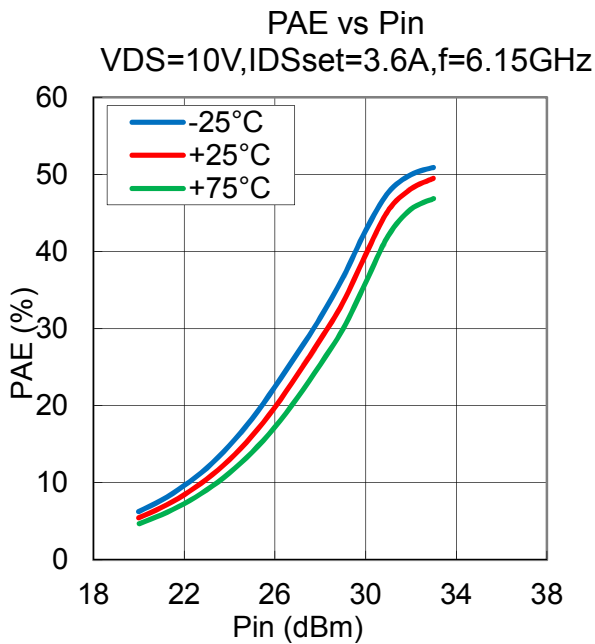
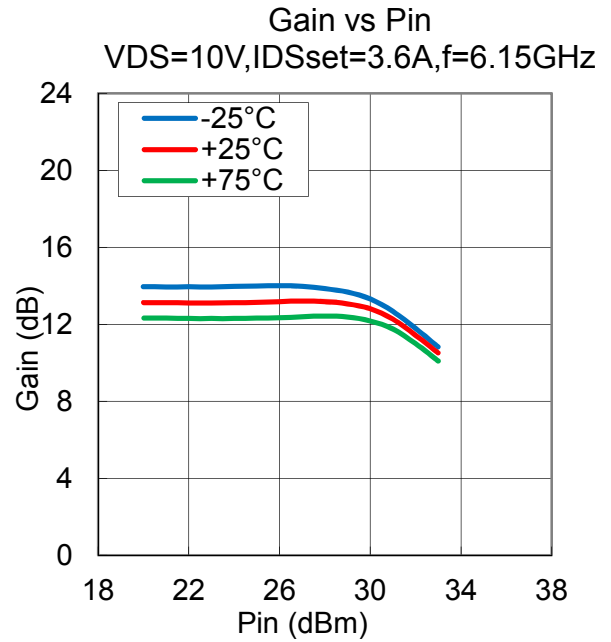
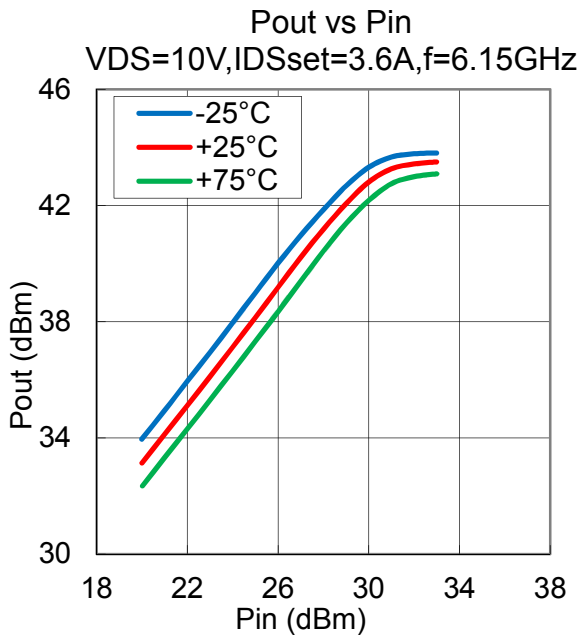


IDS vs Pin  
VDS=10V,f=6.15GHz



-Pout , Gain , PAE , IDS vs. Pin vs. Temperature

VDS= 10 V, IDSset= 3.6 A, f= 6.15 GHz, Ta= -25, +25, +75 °C



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